# **N90-2**2656

### <u>Program 4</u> Measurements and Mechanisms of Localized Aqueous Corrosion in Aluminum-Lithium Alloys

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#### **Objectives**

The objective of this research is to characterize the localized corrosion and stress corrosion crack initiation behavior of Al-Li-Cu alloy 2090, and to gain an understanding of the role of local corrosion and occluded cell environments in the mechanisms of pitting and initiation and early-stage propagation of stress corrosion cracks.

#### Stress Corrosion in 2090: The Role of Localized Corrosion in the Subgrain Boundary Region

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Like most heat treatable aluminum alloys, localized corrosion and stress corrosion of Al-Li-Cu alloys is strongly dependent on the nature and distribution of second phase particles. To develop a mechanistic understanding of the role of localized corrosion in the stress corrosion process, bulk samples of  $T_1$  (Al<sub>2</sub>CuLi) and a range of Al-Cu-Fe impurity phases were prepared for electrochemical experiments. Potentiodynamic polarization and galvanic couple experiments were performed in standard 0.6 M NaCl and in simulated crevice solutions to assess corrosion behavior of these particles with respect to the  $\alpha$ -Al matrix.

A comparison of time to failure versus applied potential using a constant load, smooth bar SCC test technique in Cl<sup>-</sup>, Cl<sup>-</sup>/CrO<sub>4</sub><sup>2-</sup> and Cl<sup>-</sup>/CO<sub>3</sub><sup>2-</sup> environments shows that rapid failures are to be expected when applied potentials are more positive than the breakaway potential ( $E_{br}$ ) of T<sub>1</sub> (crack tip) but less than  $E_{br}$  of  $\alpha$ -Al (crack walls). It is shown that this criterion is not satisfied in aerated Cl<sup>-</sup> solutions. Accordingly, SCC resistance is good. This criterion is satisfied, however, in an alkaline isolated fissure exposed to a CO<sub>2</sub> containing atmosphere. Rapid failure induced by these fissures has recently been termed "preexposure embrittlement."

Anodic polarization shows that the corrosion behavior of  $T_1$  is relatively unaffected in alkaline  $CO_3^{2-}$  environments but the  $\alpha$ -Al phase is rapidly passivated. X-ray diffraction of crevice walls from artificial crevices suggests that passivation of  $\alpha$ -Al occurs as Bayerite (Al(OH)<sub>3</sub>) imbibes solvated lithium and carbonate ions to form a hydrotalcite-type compound  $[LiAl_2(OH)_6]_2^+ \cdot CO_3^{2-} \cdot nH_2O$ . Stress Corrosion of 2090: The Role of Localized Corrosion in the Subgrain Boundary Region

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## Outline

- \* Microstructural Heterogeneity and Localized Corrosion
- \* Time to Failure vs. Applied Potential in Cl<sup>-</sup> and Cl  $^{-}/CrO_{4}^{2-}$
- \* SCC in  $CO_3^{2-}$  Environments, "Pre-Exposure Embrittlement"



Centered dark field transmission electron micrograph of the subgrain boundary region showing the precipitation of  $T_1$  on boundaries and in subgrains.

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Phase	Model Material	Corrosion Potential (mV <sub>SCe</sub> )	Galvanic Couple Current Density (ua/cm <sup>2</sup> )
a - Al	SHT 2090	-720	
Al-14Cu Al18-Cu-5Fe Al-24Cu-5Fe	as cast as cast as cast	-620 -670 -675	-0.5 -7.0 -3.0
Τ1	Al-26Cu-21Li	-1100	+ 500
PA 2090	Al-3Cu-2Li	-720	

## Corrosion Behavior in Aerated 0.6 M NaCl



- A. Optical micrograph of pitting associated with Al-Fe-Cu impurity particles.
- B. Optical micrograph of discontinuous subgrain boundary pitting associated with  $T_1$  precipitated on subgrain boundaries.





Schematic of the cell used for constant load TTF experiments.







- A. Scanning electron micrograph of the fracture surface of a 2090 tensile specimen subjected to a time to failure experiment at 55 % of the S-T yield strength in 0.1 M NaCl + 0.1 M Na  $_2$ CrO<sub>4</sub> at an applied potential greater than E<sub>br</sub> of T<sub>1</sub>.
- B. Scanning electron micrograph from the rim of the failure initiating pit.



- C. Scanning electron micrograph of the SCC propagation region 200 micrometers below the base of the pit.
- D. Scanning electron micrograph of the tensile overload region.



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Anodic polarization in 0.6 M NaCl solution

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# Time to Failure vs. Applied Potential in Aerated 0.6 M NaCl

Applied Potential (mV <sub>sce</sub> )	Time to Failure (days)
-720 (E <sub>corr</sub> )	3 @ > 75 5 @ > 30
-715	2 @ > 45
-1150	2 @ > 45



- A. Scanning electron micrograph of the fracture surface of a 2090 specimen loaded to 55% of the S-T yield and immersed in 0.6 M NaCl solution under free corrosion conditions for 7 days then removed from solution and pulled to fracture in air.
- B. Scanning electron micrograph of the failure initiating pit.



C. Scanning electron micrograph of the overload region directly below the base of the pit.

Necessary Conditions for Rapid SCC Failure Appear to be:

- \* $\alpha$  Al passive (below  $E_{br}$ )
- \*  $T_1$  transpassive (above  $E_{br}$ )

### Pre-Exposure Embrittlement



- \* Alloy 8090, Holroyd, et al. (1987)
- \* Alloy 2090, Moran (1989)



Moran

Holroyd, et al.

Corrosion Behav	ior in Cl <sup>-</sup>	and	$CI^{-}/CO_{3}^{2-}$
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	phase	<sup>i</sup> pass (ua/cm <sup>2</sup> )	E <sub>br</sub> (mV <sub>sce</sub> )
0.6 M NaCl	a - Al	1.0	-690
pH = 7-8	T <sub>1</sub>	200	-720
0.6 M NaCl + 0.1 M Li <sub>2</sub> CO <sub>3</sub>	द्र - Al	0.75	-590
pH = 10	T <sub>1</sub>	550	-720

-590 mV > Rapid Failure > -720 mV Window



Time to failure versus applied potential in Cl  $^{-}/CO_{3}^{2-}$ 



Open circuit potential versus time in  $CI^{-}/CO_{3}^{2-}$ 



- A. Scanning electron micrograph of the film that forms in the SCC region of a 2090 tensile specimen where the specimen is immersed in aerated 0.6 M NaCl for 7 days then removed to  $CO_2$  -free air.
- B. Scanning electron micrograph of the film that forms in the SCC region of a 2090 tensile specimen that is immersed in aerated 0.6 M NaCl for 7 days then removed to laboratory air.

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\* derived from bayerite AI(OH)3

## Hydrotalcites

- \* Alumina Gels + Lithium Salts  $\longrightarrow$  (LiX<sub>x</sub>)<sub>y</sub> · 2(AlOH)<sub>3</sub> · nH<sub>2</sub>O
- \* Several anions produce isomorphous compounds

- \* Passivating effects associated with its presence (Perrota, 1990)
- \* Insoluble in alkaline solutions



### Ammended Pre-Exposure Embrittlement Mechanism



### Summary

- \* In order of increasing nobility: T<sub>1</sub> < *A* - Al < Al-Cu-Fe
- \* Rapid SCC ensues when: E br T > E applied > E br < - Al
- \* In 0.6 M NaCl, E<sub>br</sub>T<sub>1</sub> = E<sub>br</sub> ≺ Al rapid SCC criterion is not satified
- \* In isolated fissures, rapid SCC criterion is satisfied
- \* *a* Al is passivated by a hydrotalcite-type compound

The following pages are from a presentation given at the CORROSION/90 Meeting, April 23-27, Las Vegas, Nevada

# The Role of Hydrolysis in Crevice Corrosion of Aluminum-Lithium-Copper Alloys

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## Overview

\* Background

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- \* Objectives
- \* Approach
- \* Results
- \* Summary

### Background





dissolution in the crevice

reduction reactions outside the crevice



dissolution in the crevice

reduction reactions inside crevice

# Objectives

Separate and identify the roles of:

-

• 
$$Al^{3+}$$
  
•  $Li^{+}$  hydrolysis  
•  $Cu^{2+}$ 

\* an external cathode

### Approach

Simulated crevice technique

- \* in situ measurement
- avoid the size constraint associated with real crevices



Measure pH versus Time for:

<u>Materials</u>

**Environments** 

99.99 Al SHT Al-3Li SHT Al-3Cu SHT Al-3Cu-2Li

Aerated Bulk Solution Isolated Crevice

### Approach

Interpret steady state pH using Distribution Diagrams for monomeric hydrolysis products and knowledge of where electrochemical reduction reactions are occurring.

Monomeric Hydrolysis

$$xM^{z+} + yH_2O \iff M_x(OH)_y(xz-y) + yH^+$$

- \* Rapid  $10^5 < k < 10^{10} \text{ moles}^{-1} \text{sec}^{-1}$
- \* Reversible
- \* An equilibrium treatment is applicable

### **Reactions Considered**

 $Li^+ + H_2O \Leftrightarrow LiOH + H^+$  13.86

### <u>Copper</u>

$Cu^{2+} + H$	$H_2O \leftrightarrow CuOH^+ + H^+$	8.0
$Cu^{2+} + 2$	$2H_2O \leftrightarrow Cu(OH)_2 + 2H^+$	17 2

$$Cu^{2+} + 2H_2O \iff Cu(OH)_2 + 2H^+$$

$$Cu^{2+} + 3H_2O \iff Cu(OH)_3^- + 3H^+$$

$$Cu^{2+} + 4H_2O \iff Cu(OH)_4^{2-} + 4H^+$$

$$Su^{2+} + H_2O \iff 1/2Cu_2(OH)_2^{2+} + H^+$$

$$10.36$$

### Electrochemical Reactions

$M \rightarrow M^{n+} + ne^{-}$	internal
$O_2 + 4H^+ + 4e^- \rightarrow 2H_2O$	external
$2H^+ + 2e^- \rightarrow H_2$	internal
$H_2O + e^- \rightarrow H + OH^-$	internal

# **Construction of Distribution Diagrams**

Formation Quotients (Baes and Mesmer, 1986.)

$$\log Q_{xy} = \log K_{xy} + \frac{aI^{1/2}}{(1 + I^{1/2})} + bI$$

$$I = \sum \frac{\sum z_i^2[i]}{2}$$

Mass Action Expressions

$$Q_{11} = \frac{[AlOH^{2+}][H^{+}]}{[Al^{3+}]}$$
  
:  
:  
 $F_{AlOH}^{2+} = [AlOH^{2+}]$ 

Σ[species]

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Hydrolysis Reaction:

$$Al^{3+} + H_2O \Leftrightarrow AlOH^{2+} + H^+$$

pH determined by  $[Al^{3+}]/[AlOH^{2+}]$  in this range

internal



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 $3H^+ + 3e^- \rightarrow 3/2H_2$ 

dissolution of 1 Al consumes 3 H<sup>+</sup>

Hydrolysis Reactions:

$$Al^{3+} + H_2O \rightarrow AlOH^{2+} + H^+$$

$$Al^{3+} + 2H_2O \rightarrow Al(OH)_2^+ + 2H^+$$

$$Al^{3+} + 3H_2O \rightarrow Al(OH)_3 + 3H^+$$

$$Al^{3+} + 4H_2O \leftarrow Al(OH)_4^- + 4H^+$$
net gain of 1 H<sup>+</sup>



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internal

**Results for SHT Al-3Li** 



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Reduction kinetics are slowed at the external cathode.





# Electrochemical Reactions:

$Li \rightarrow Li^+ + e^-$	internal
$H^+ + e^- \rightarrow 1/2H_2$	internal
$H_2O + e^- \rightarrow H + OH^-$	internal

dissolution of 1 Li consumes 1 H<sup>+</sup>

8

P

10

Hydrolysis Reactions:  $Li^+ + H_2O \Leftrightarrow LiOH + H^+$ no net loss of H<sup>+</sup> 100 90 Percent Hydrolysis Product & & & & & & & 80 ц+ 70 60 50 AL(OH) LOE 10 0 6 7

11 pH

12

13

14

15

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### **Results for SHT AI-3Cu**



### Aerated Bulk Solution

Consistent with  $Al^{3+} + H_2O \Leftrightarrow AlOH^{2+} + H^+$  equilibrium.

Isolated Crevice

### **Electrochemical Reactions:**

$Cu \rightarrow Cu^{2+} + 2e^{-}$	internal
$2H^+ + 2e^- \rightarrow H_2$	internal

dissolution of 1 Cu atom form the alloy consumes 2 H<sup>+</sup>.

### Copper oxidation can not discharge H<sup>+</sup>.

In RRDE experiments with  $Al_2Cu$  at potentials below  $E_{R Cu/Cu}^{2+}$ , copper deposits have been observed. (Mazurkiewicz and Piotrowski, 1983).



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### Aerated Bulk Solution

Consistent with  $Al^{3+} + H_2O \Leftrightarrow AlOH^{2+} + H^+$  equilibrium.

Isolated Crevice

$$Li \rightarrow Li^+ + e^-$$

$$H^+ + e^- \rightarrow 1/2H_2$$

assisted by elemental Cu on walls

 $Li^+ + H_2O \Leftrightarrow LiOH + H^+$ 

replaces H<sup>+</sup> and inhibits further pH increase.

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### Summary

\* In aerated bulk solutions, crevice pH is consistent with:

 $Al^{3+} + H_2O \Leftrightarrow AlOH^{2+} + H^+$ 

dependent on reduction kinetics at the external cathode.

- \* Al(OH)<sub>2</sub> <sup>+</sup>/Al(OH)<sub>4</sub><sup>-</sup> system point defines the pH in pure Al, isolated crevices.
- \* Li  $\rightarrow$  Li<sup>+</sup> + e<sup>-</sup> H<sup>+</sup> + e<sup>-</sup>  $\rightarrow$  1/2H<sub>2</sub> gives an alkaline crevice Li<sup>+</sup> + H<sub>2</sub>O  $\leftrightarrow$  LiOH + H<sup>+</sup> replaces H<sup>+</sup>
- \* Elemental Cu on walls of crevices may assist in generating alkaline crevice solutions.